

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (currently amended) An interconnect structure ~~for receiving a solder contact~~ comprising:  
a substrate;  
a conductive contact pad disposed over a portion of the substrate surface; ~~of the substrate~~  
having an inner portion and an outer portion surrounding the inner portion;  
[[an]] the inner portion of the contact pad [[including]] having a compliant layer under  
the contact pad and the outer portion of the contact pad not including a compliant layer  
~~and a conductive layer that is disposed over the compliant layer;~~  
the portion of the contact pad over the compliant layer having a thickness thinner than the  
thickness of the outer portion of the contact pad; and  
an insulative mask disposed over the contact pad, the insulative mask including an opening that is aligned over and that exposes the inner portion, the inner portion of the contact pad having sufficient flexibility to distribute mechanical stress applied to the contact pad.
2. (currently amended) The interconnect structure of claim 1, the compliant layer being formed from a compliant material that has an elastic modulus lower than the elastic modulus of the material used to form the [[conductive layer]] contact pad.
3. (currently amended) The interconnect structure of claim 2, the [[conductive layer]] contact pad comprising a conductive metal and the compliant layer comprising at least one of a metal, a non-metal, a ceramic, and a composite.
4. (currently amended) The interconnect structure of claim 1, the [[conductive layer]] contact pad comprising copper and the compliant layer comprising a compliant material having an elastic modulus lower than the elastic modulus of copper.

5. (currently amended) The interconnect structure of claim 1, the compliant layer being more flexible than the ~~[[conductive layer]]~~ contact pad and being formed from a compliant material that has an elastic modulus higher than the elastic modulus of the material used to form the ~~[[conductive layer]]~~ contact pad.
6. (currently amended) The interconnect structure of claim 5, the compliant layer comprising at least one of pores, apertures, and voids to provide the compliant layer with a flexibility greater than the ~~[[conductive layer]]~~ contact pad.
7. (canceled)
8. (currently amended) The interconnect structure of claim ~~[[7]]~~ 1, the ~~[[conductive layer of the]]~~ inner portion of the contact pad being substantially more flexible than ~~the at least one conductive layer of the outer portion.~~
9. (original) The interconnect structure of claim 1, the opening exposing a substantially planar contact surface.
10. (original) The interconnect structure of claim 1 further including a solder contact attached to the contact surface, the solder contact including a contact portion defined by the opening of the insulative mask.
11. (currently amended) The interconnect structure of claim 10, the contact surface including at least one protrusion that extends within the opening from the contact surface, the protrusion being defined by the ~~conductive layer of the inner portion~~ compliant layer.
12. (canceled)

13. (currently amended) An interconnect structure ~~for receiving a solder contact~~ comprising:

a substrate;

a conductive contact pad disposed over a portion of the substrate surface, ~~of the substrate~~ having an inner portion and an outer portion surrounding the inner portion;

[[an]] the inner portion of the contact pad ~~[[including]]~~ having a compliant layer under the contact pad and the outer portion of the contact pad not including a compliant layer ~~and a conductive layer that is disposed over the compliant layer;~~

the portion of the contact pad over the compliant layer having a thickness thinner than the thickness of the outer portion of the contact pad; and

an insulative mask disposed over the contact pad, the insulative mask including an opening that is aligned over and that exposes a contact surface of the contact pad, the contact surface being defined by the inner portion and part of the outer portion.

14. (currently amended) The interconnect structure of claim 13, the compliant layer being formed from a compliant material that has an elastic modulus lower than the elastic modulus of the material used to form the ~~[[conductive layer]]~~ contact pad.

15. (currently amended) The interconnect structure of claim 13, the ~~[[conductive layer]]~~ contact pad comprising copper and the compliant layer comprising a compliant material having an elastic modulus lower than the elastic modulus of copper.

16. (currently amended) The interconnect structure of claim 13, the compliant layer being more flexible than the ~~[[conductive layer]]~~ contact pad and being formed from a compliant material that has an elastic modulus higher than the elastic modulus of the material used to form the ~~[[conductive layer]]~~ contact pad.

17. (canceled)

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18. (currently amended) The interconnect structure of claim 11, the [[conductive layer]] contact pad of the inner portion being substantially more flexible than the ~~at least one conductive layer of the~~ outer portion.

19. (currently amended) The interconnect structure of claim 13, the contact surface including at least one protrusion that extends within the opening from the contact surface, the protrusion being defined by a surface of the [[conductive layer of the]] inner portion of the contact pad.

20. (currently amended) The interconnect structure of claim 19 further including a solder contact attached to the contact surface, the solder contact including a contact portion defined by the opening of the insulative mask.

21-27. (canceled)